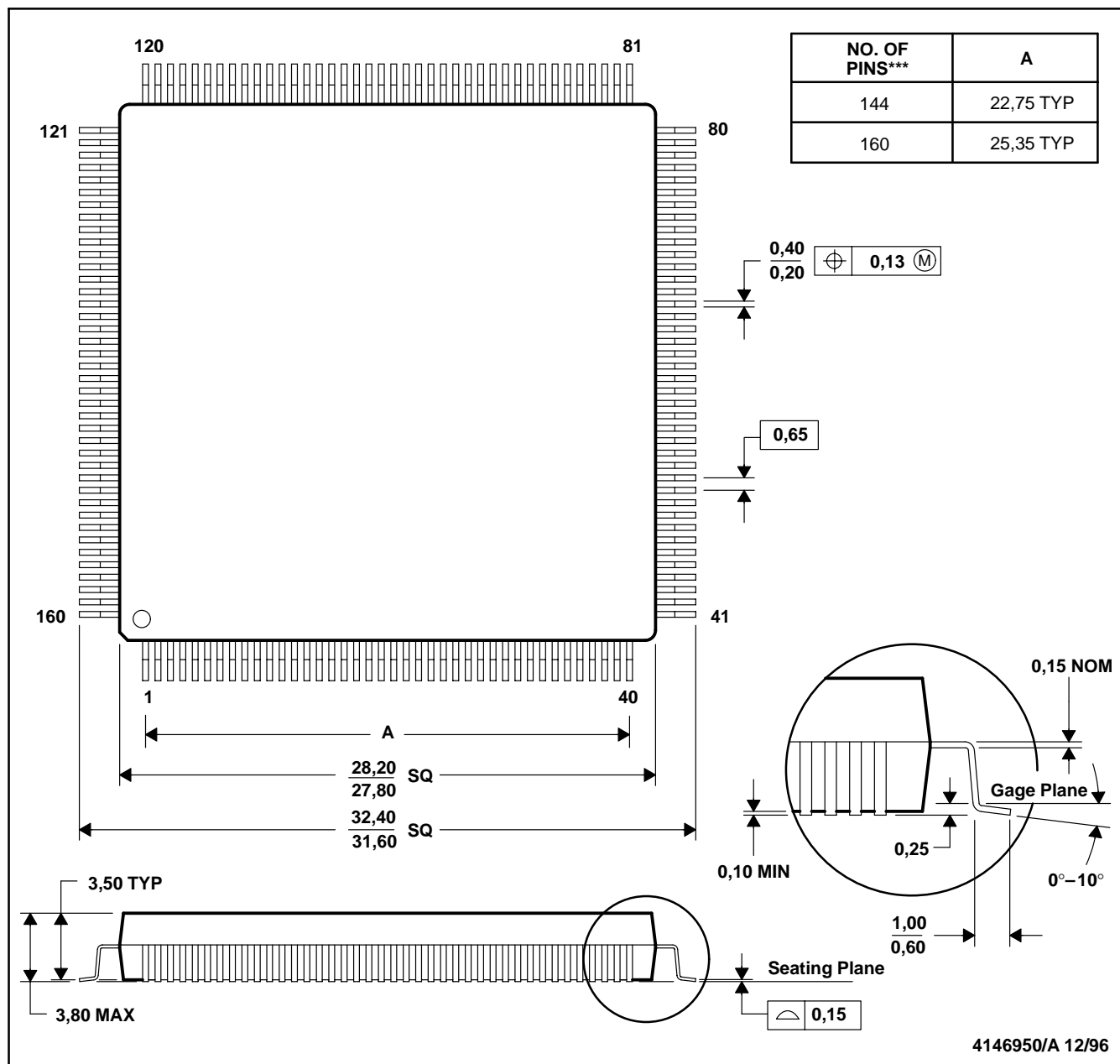


PCH (S-PQFP-G***)

PLASTIC QUAD FLATPACK

160 PIN SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Contact field sales office to determine if a tighter coplanarity requirement is available for this package.
 - Thermally enhanced molded plastic package with a heat spreader (HSP).

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